

EV Group

Dr. Werner Thallner
Executive Operations and Financial Director
EV Group



会社概要・沿革

- 半導体・MEMS及びナノテクノロジー産業におけるウェーハプロセスのソリューションを世界中に提供する装置メーカー
- ウェーハ貼り合わせ市場では、圧倒的なシェアを誇り、先端パッケージングやナノテクノロジー市場におけるリソグラフィ装置のリーディングカンパニー
- 1980年に設立。本社オーストリア(St. Florian)をはじめとし、米国・日本・韓国・台湾にある支店を通じ、販売及びカスタマーサポートを世界中で展開
(従業員数:約450名)
- 主要実績:
 - 1985年 世界初の裏面顕微鏡による両面マスクアライナーを開発
 - 1990年 ウェーハ位置合わせと貼り合わせのプロセス分離を考案
 - 1999年 SmartView®ウェーハ・ツール・ウェーハ対面アライナーを発表
 - 2007年 世界初300mmウェーハ対応全自動ウェーハ接合装置を発表



EV Group Headquarters



EV Group Japan KK, Yokohama

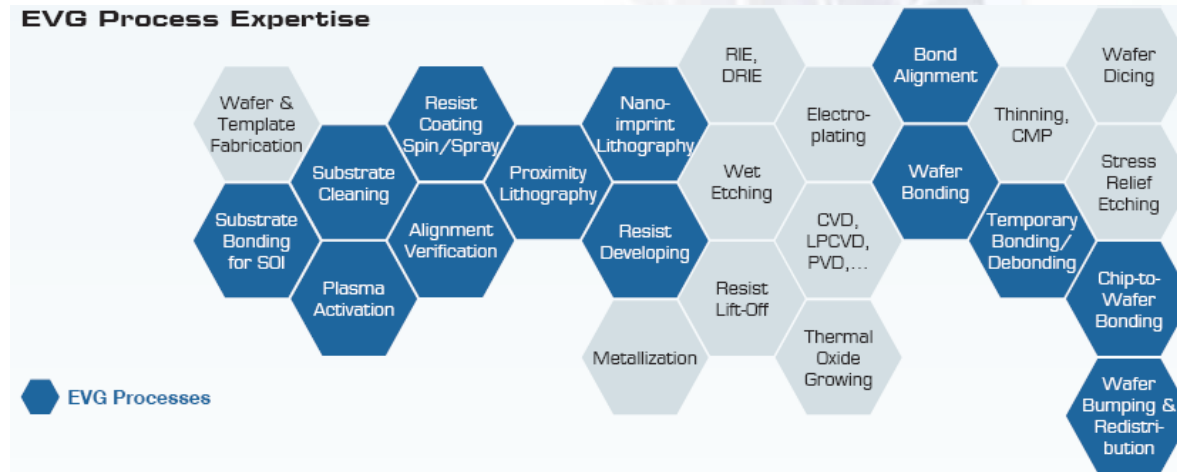


Cleanrooms and Application Labs



研究開発への貢献

- EV Groupは、300mmウェーハレベルでの半導体・MEMSプロセスに対応する装置とプロセスポートフォリオをご提供します。



- EV Groupは、主要大学や研究機関との技術コンソーシアムや共同開発プログラムに売上の20%以上を継続的に投資し、重要な役割を果たしています。



Consortium for Commercialization of Nano Imprint Lithography (NIL)



Semiconductor 3-D Equipment and Materials Consortium



Interessengemeinschaft zur Verbreitung von Anwendungen der Mikrostrukturtechniken



Micro And Nanotechnology Commercialization Education Foundation



MEMS Industry Group



Österreichische Gesellschaft für Mikrosystemtechnik



Optical Society of America



Semiconductor Equipment and Materials International



製品ラインナップ及び実績

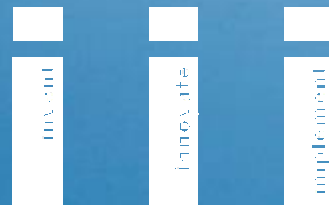
- R&D及び量産工場への装置導入実績は1400台を超え、ウェーハ貼り合わせ市場では、圧倒的なシェアを獲得。また先端パッケージングやナノテクノロジー市場においてはリソグラフィー装置のリーディングカンパニーとなっております。

LITHOGRAPHY BONDING

<p>MASK ALIGNMENT SYSTEMS</p> <p>EVO®200 Semi-Automated Mask Alignment System up to 150mm EVO®202NT Automated Mask Alignment System up to 200mm EVO®200P Automated Mask Alignment System up to 200mm EVO®202NT Semi-Automated Mask Alignment System up to 200mm IO Aligner® Automated Mask Alignment System up to 200mm</p>	<p>WAFER BONDING SYSTEMS</p> <p>EVO®201 Wafer Bonding System up to 200mm EVO®210 Semi-automated Wafer Bonding System up to 200mm EVO®203S Semi-automated Wafer Bonding System up to 200mm EVO®240 Automated Wafer Bonding System up to 200mm EVO®240CW Automated Wafer & Chip-to-Wafer Bonding System up to 200mm EVO®260 Automated Wafer Bonding System up to 200mm</p>
<p>RESIST PROCESSING SYSTEMS</p> <p>EVO®101 Advanced Resist Processing System up to 200mm EVO®105 Bake Module up to 200mm EVO®101LA Large Area Coating System for > 200mm EVO®120 Automated Resist Processing System up to 200mm EVO®130 Automated Resist Processing System up to 200mm</p>	<p>BOND ALIGNMENT SYSTEMS</p> <p>EVO®210 Semi-automated Bond Alignment System up to 150mm EVO®200 Semi-Automated Bond Alignment System up to 200mm EVO®200P Semi-Automated Bond Alignment System up to 200mm SmartView® Automated Bond Alignment System for Universal Alignment up to 200mm SmartView®XT Automated Bond Alignment System for Universal Alignment up to 200mm</p>
<p>LITHOGRAPHY TRACK SYSTEMS</p> <p>HENGULES® Lithography Track System coalign & expose/develop configuration up to 200mm HENGULES®L Lithography Track System resist processing & expose configuration up to 200mm EVO®101LA Large Area Resist Processing System up to 200mm EVO®130M Automated NanoSpray Coating System up to 200mm</p>	<p>INTEGRATED BONDING SYSTEMS</p> <p>GEMIN® Automated Production Wafer Bonding System up to 200mm GEMIN® Automated Production Wafer Bonding System up to 200mm GEMIN® Automated Production Fusion Bonding System up to 200mm GEMIN® Automated Production Fusion Bonding System up to 200mm</p>
<p>NANOIMPRINT LITHOGRAPHY SYSTEMS (UV-NIL, μ-CP, HE)</p> <p>EVO®200 Semi-Automated UV-NIL, μ-CP System up to 150mm EVO®202NT Semi-Automated UV-NIL, μ-CP System up to 150mm EVO®200P Semi-Automated UV-NIL, μ-CP System up to 200mm EVO®202NT Semi-Automated UV-NIL, μ-CP System up to 200mm IO Aligner® Automated UV-NIL, μ-CP System up to 200mm EVO®710 Automated NIL Stepper up to 200mm</p>	<p>SOI BONDING SYSTEMS</p> <p>EVO®200 Semi-automated Single Wafer Cleaning System up to 200mm EVO®200 Automated Single Wafer Cleaning System up to 200mm EVO®200 Plasma Activation System up to 200mm EVO®200 Automated Production Bonding System for SOI and Direct Wafer Bonding up to 200mm EVO®200 Automated Production Bonding System for SOI and Direct Wafer Bonding up to 200mm</p>
<p>INSPECTION SYSTEMS</p> <p>EVO®40 Semi-automated Top-to-Bottom Side Measurement System up to 200mm EVO®40 Advanced Manual Top-to-Bottom Side Measurement System up to 200mm EVO®200 Automated Measurement System up to 200mm EVO®200 Semi-Automated Measurement System up to 200mm EVO®200 Automated Measurement System up to 200mm</p>	<p>TEMPORARY BONDING and DEBONDING SYSTEMS</p> <p>EVO®200 Semi-automated Debonding System up to 200mm EVO®200 Lamination System up to 200mm EVO®200 Automated Temporary Bonding System up to 200 EVO®200 Automated Temporary Bonding System with Integrated Lamination System up to 200mm EVO®200 Automated Debonding System up to 200mm</p>
<p>INSPECTION SYSTEMS</p> <p>EVO®200 PT Inspection Station up to 200mm EVO®200 Automated Measurement System up to 200mm</p>	

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Triple i - The key to your success

